

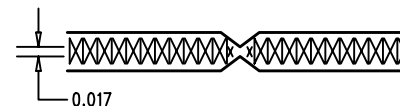
SHOWN FROM COMPONENT SIDE

REVISIONS			
	DESCRIPTION	APPR	DATE
REV A	PROTOTYPE RELEASE		


SIZE	QTY	SYM	PLTD
0.035	127	+	PLTD
0.055	10	×	PLTD
0.094	13	□	PLTD
0.19	2	◇	PLTD
0.1	2	⊗	NPLTD
0.125	4	⊗	NPLTD
0.25	1	A	NPLTD
0.015	817	B	PLTD

NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD THICKNESS .062 +/- .006 TOTAL OF 8 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE ELECTRODEPOSITED TIN-LEAD COMPOSITION BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
	INIT	DATE		
DRAWN			TITLE: FABRICATION DRAWING SINGLE PHASE IMVP4 POWER SUPPLY	
CHECK				
DESIGN	KIM T.	01-24-03		
ENGR	WEI C.	01-24-03		
			SIZE A	REV. A
SCALE = NONE			DES- 0000	SHT 1 of 1